

ABSTRACT OF THE DISCLOSURE

The present invention provides the miniaturization and weight reduction of the multi-layer circuit board and improvement in the processability thereof. The multi-layer circuit board comprises a substrate 10, on at least one surface of a substrate 10, a first electrical conductive circuit (metal plating film 30) disposed on the substrate 10, an resin layer 20 disposed on the first electrical conductive circuit and a second electrical conductive circuit (metal plating film 30) disposed on the resin layer. The resin layer 20 is composed of a resin compound including benzocyclobutene resin, particulate inorganic filler and ultraviolet absorbent.